

**CHEMICAL MACHINE POLISHING DEVICE**

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**Abstract**

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**PROBLEM TO BE SOLVED:** To provide a CMP device for achieving a global and flat polished surface by setting the ratio of a slurry when not used to that when used to be uniform in a plane of a wafer.  
**SOLUTION:** A polishing pad 2 with a groove 5 engraved is mounted on a rotatable platen 1 and a wafer 4 is mounted on the lower face of a rotatable wafer holding plate 3. By applying a load on the wafer holding plate 3, the wafer 4 is thrust against the polishing pad 2. The platen 1 has a slurry supply hole 6 and a slurry discharge hole 7 in communication with the groove 5 formed in the polishing pad 2 for the supply and discharge of a slurry. The slurry is supplied via the slurry supply hole 6 into the groove 5, part of which overflows from the groove and moves onto the polishing pad for use in polishing. The used slurry flows into the groove 5 and is then discharged via the slurry discharge hole 7.

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